

## Recommended Reflow Profile

Applicable Products	All ASB's Plastic Encapsulated Packages – SOT89, SOT363, SOT343, SOIC8, DFN6, TDFN8, TDFN10, UQFN-6, UQFN-14L, TSSOP24, QFN24
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All ASB's plastic encapsulated packages are lead-free finished by pure matte tin (Sn). This pure matte Sn provides a stable plating for both of SnPb alloy solder process and Pb-free alloy solder process. The recommended reflow profile investigated by ASB for our plastic encapsulated packages is schematized below.

